

TIDA-00382 Board Layout

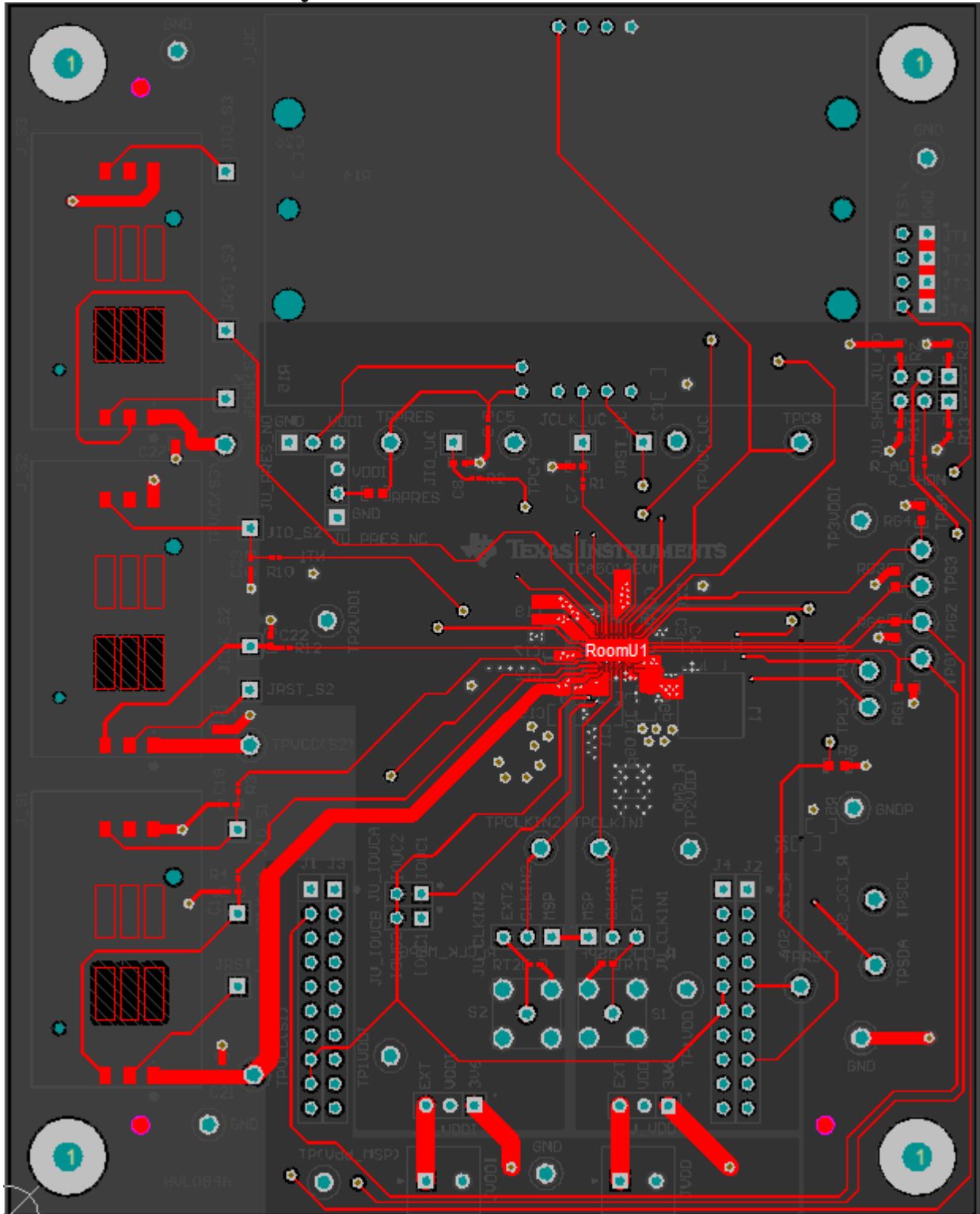


Figure 1. PCB Layer 1 (Top Layer)

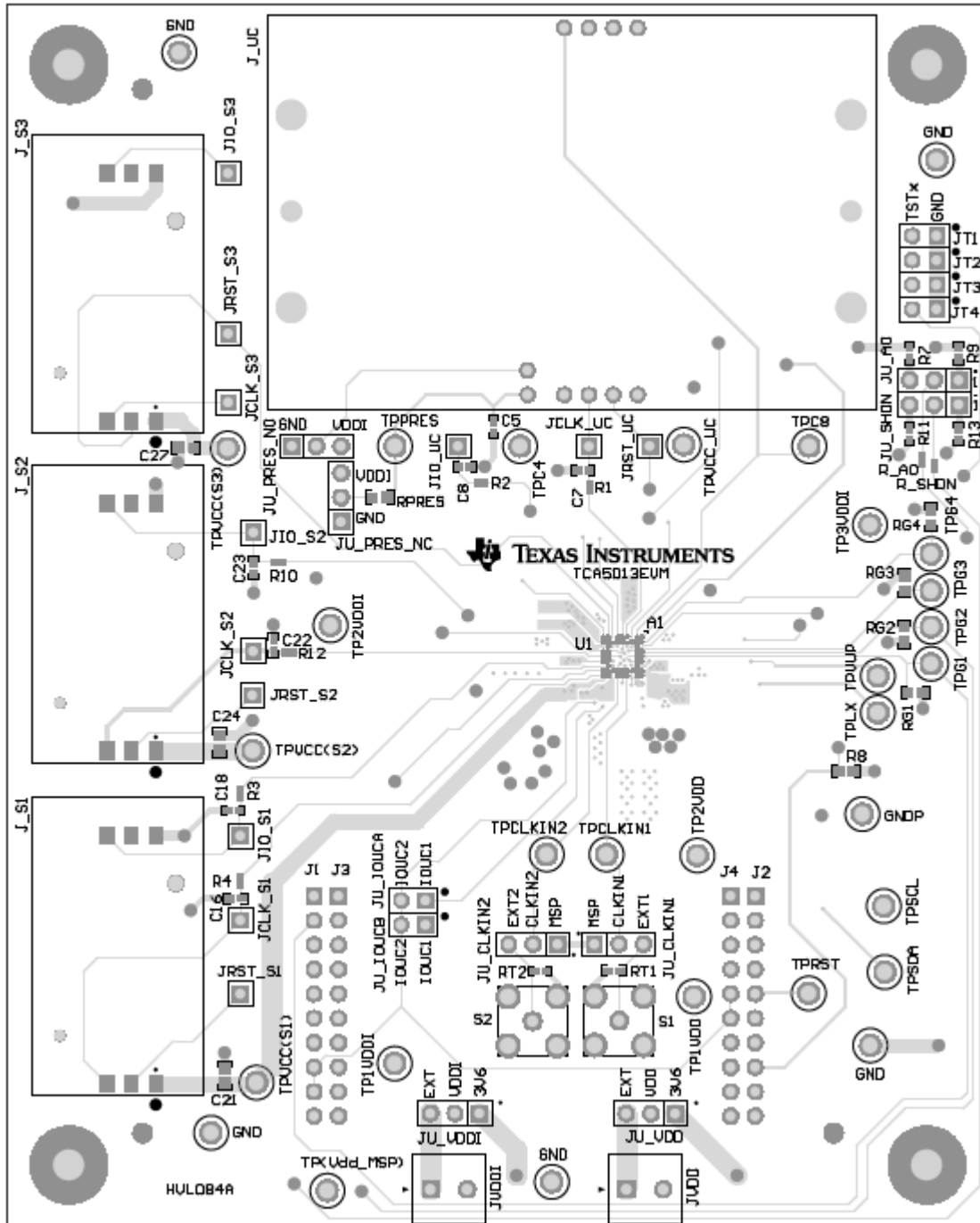


Figure 2. PCB Layer 1 (Component View)

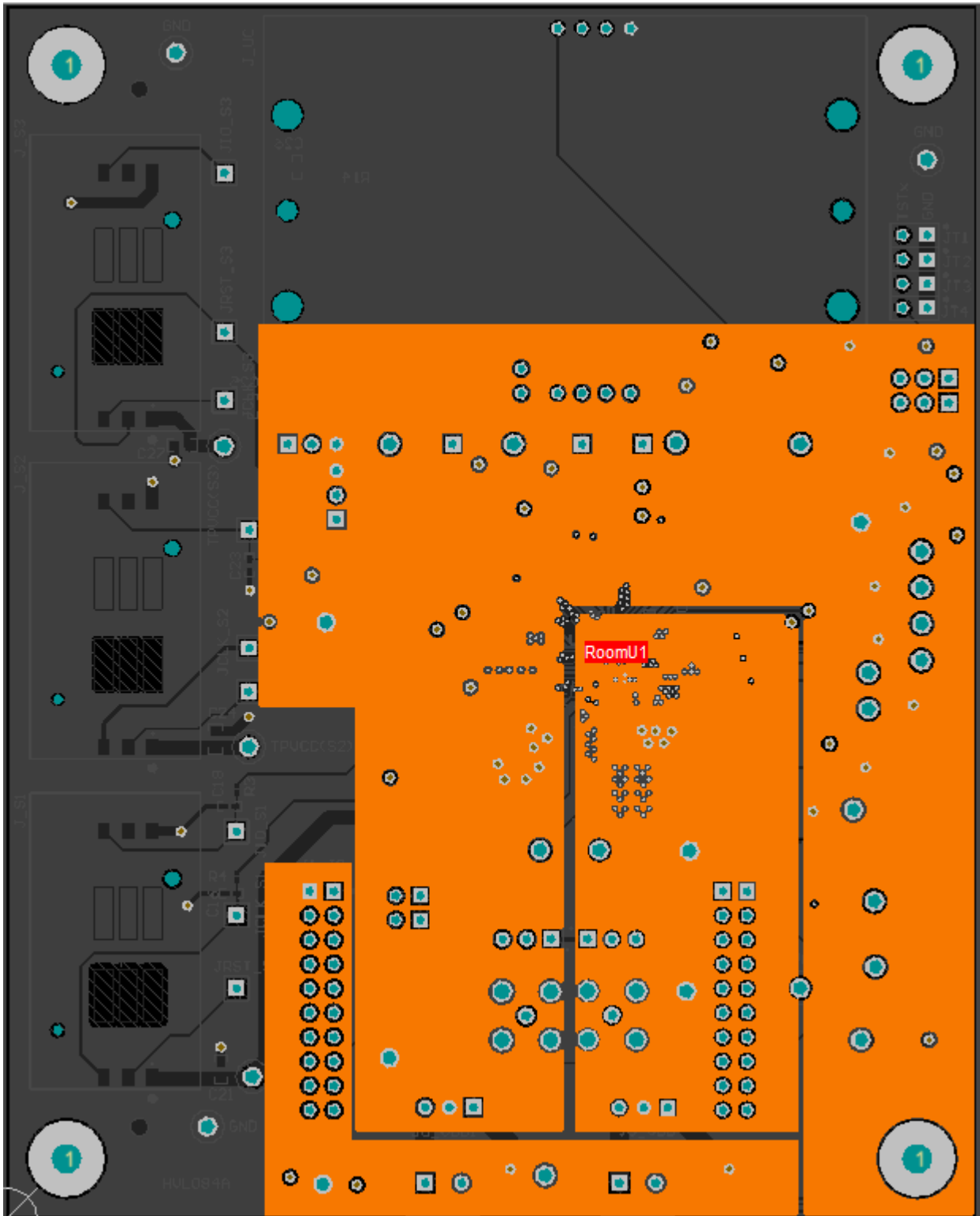


Figure 3. PCB Layer 2 (VDD Plane)

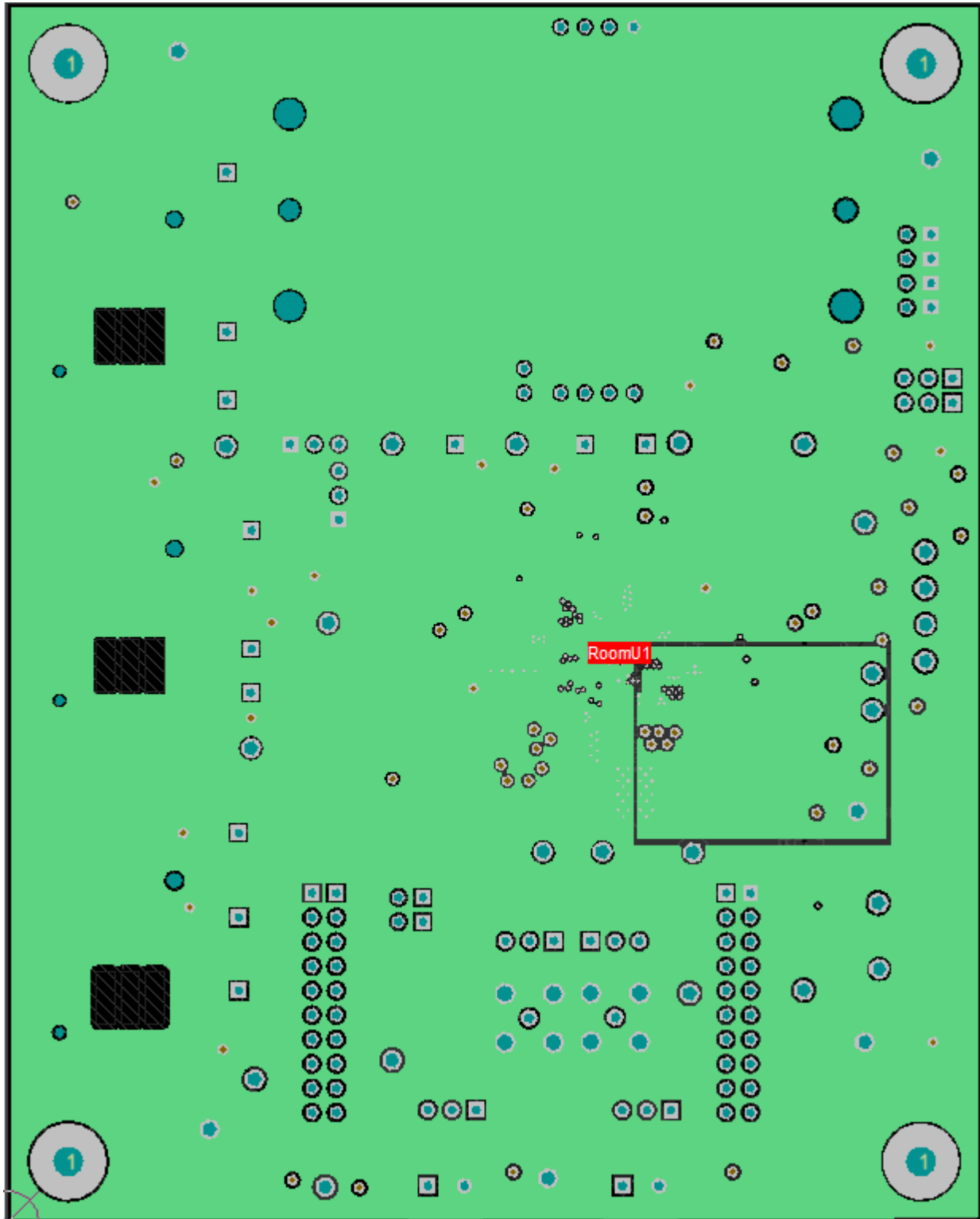


Figure 4. PCB Layer 3 (GND Plane)

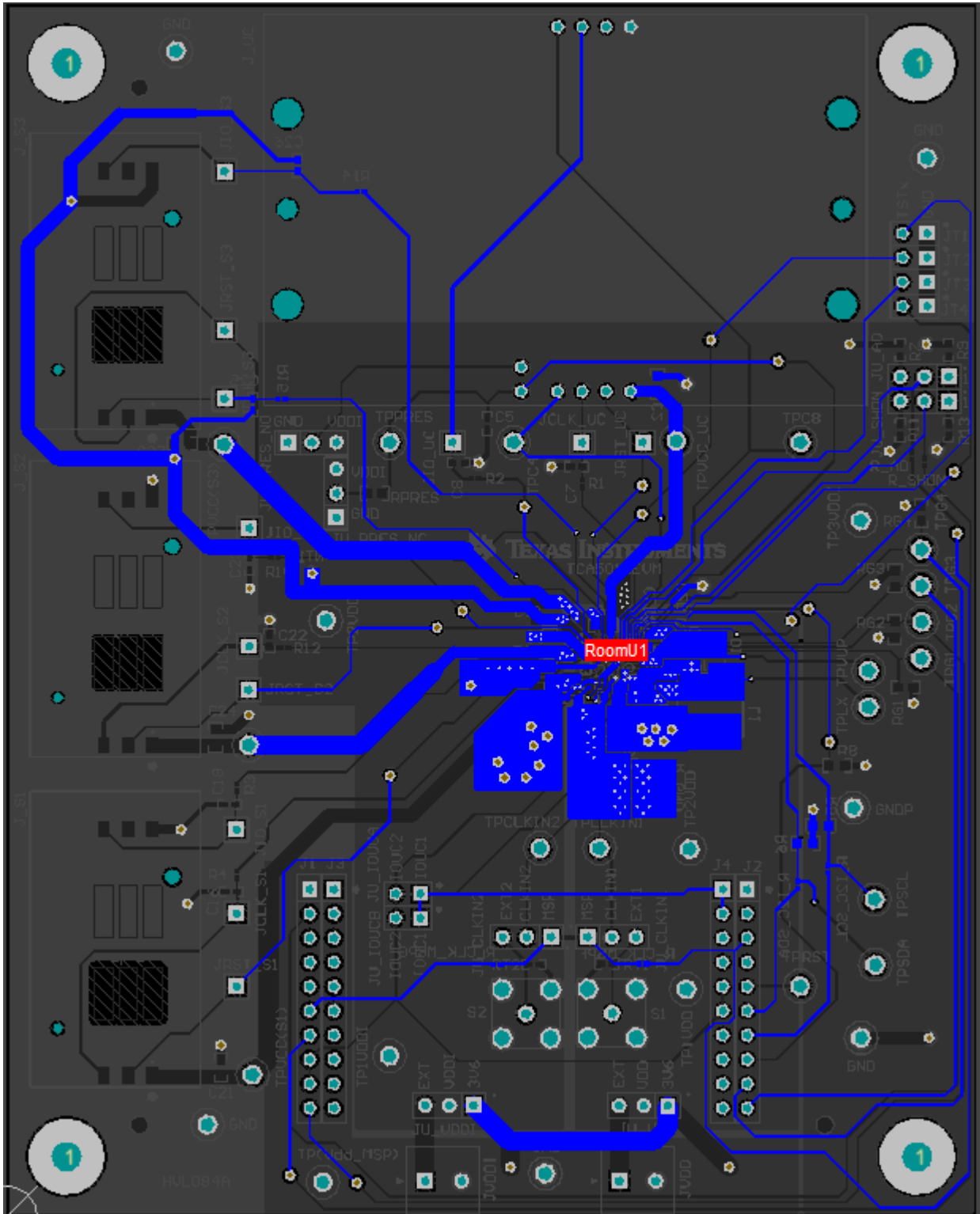


Figure 5. PCB Layer 4 (Bottom Layer)

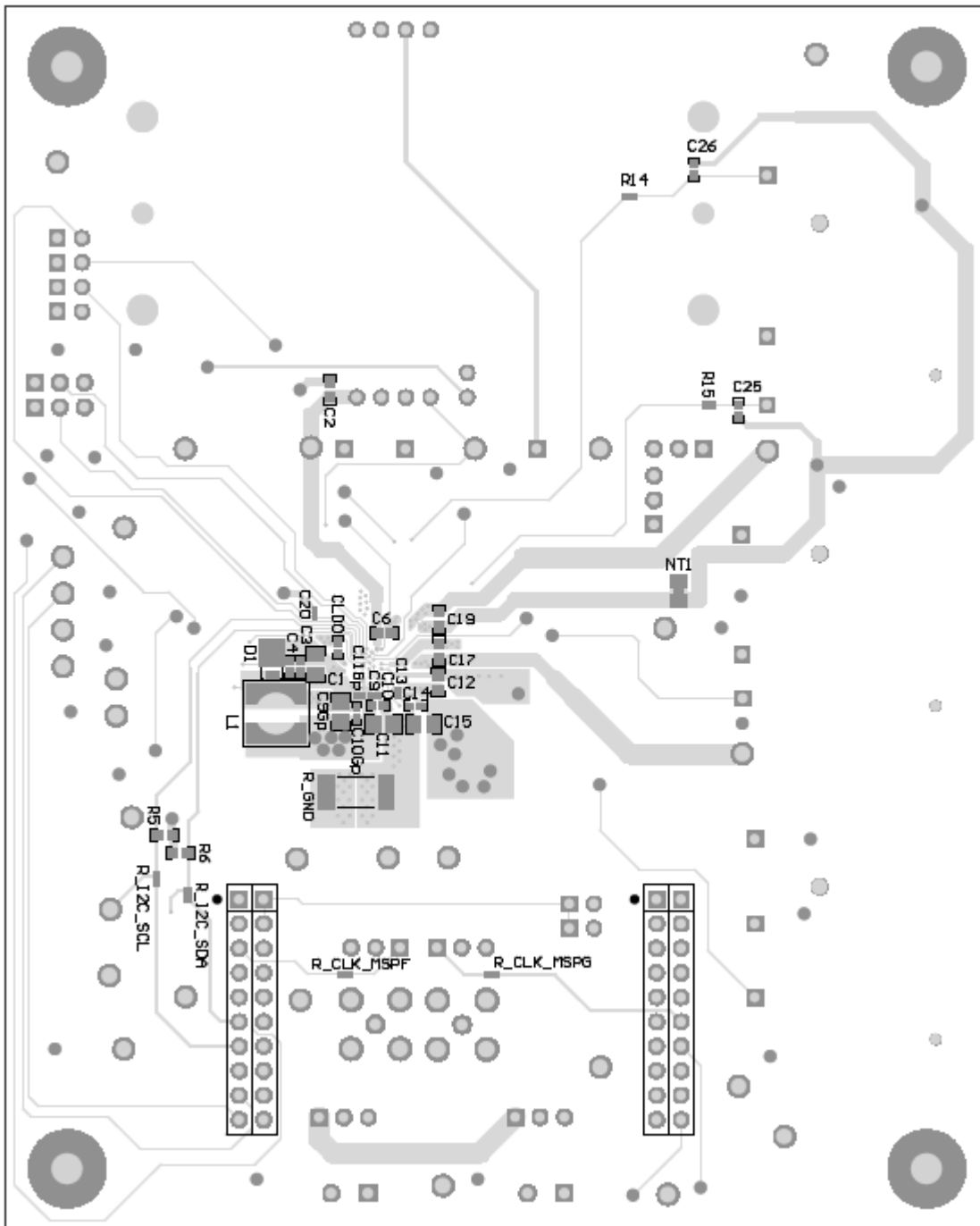


Figure 6. PCB Layer 4 (Component View)

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